

2ND TOPICAL MEETING ON Electrical Performance of Electronic Packaging

October 20 – 22, 1993
Monterey, California

FIRST CALL FOR PAPERS

Co-Chairs: G. Arjavalingam, IBM T.J. Watson Ctr., A. Cangellaris, University of Arizona

The general subject of the meeting is the electrical design, analysis, and characterization of interconnections and packaging for performance-driven, high-speed/high complexity electronic systems. A forum will be provided for the discussion of the following topics as they relate to chip-to-chip and on-chip interconnections in electronic and microwave systems:

- Electrical requirements, limits of performance.
- Novel designs, design methods, wire placement and routing programs.
- Package analysis, including numerical methods and algorithms; electromagnetic analysis tools; advances in transmission-line techniques.
- New and innovative interconnect and packaging structures and their electrical performance; packaging considerations for parallel computers.
- Experimental characterization techniques and testing procedures.
- EMC/EMI effects; prediction and measurement of radiation from interconnect structures.
- Optoelectronic packaging; structures and system applications.

This is the second meeting in this topical series. The first was held in Tucson, Arizona during April 22-24, 1992. Additional information may be obtained from G. Arjavalingam, (phone 914-945-1359, FAX 914-945-2141) or A. Cangellaris, (phone 602-621-4521, FAX 602-621-8076).

Authors are invited to submit papers describing new technical contributions in the areas broadly covered above. The original and three copies of a **35-word abstract** and a **summary** not to exceed **three pages**, including illustrations, are required for paper selection. All papers must be written in English. The title of the paper and the names and affiliations of all the authors including complete mailing address, telephone and FAX number (if available), must appear on the abstract and the first page of the summary. If the paper is accepted, the summary will be reproduced, as is, in the meeting's digest. **An IEEE transfer of copyright, found in most IEEE journals, must accompany each submission.**

Submission should be sent, no later than **June 14, 1993**, to:

EPEP '93
Engineering Professional Development
University of Arizona
Box 9 Harvill Building, Room 235
Second and Olive Streets
Tucson, Arizona 85721

PRODUCT DISPLAYS: Parties interested in displaying products at this meeting should contact the address above.

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